

Special Issue on

Welding and Soldering Materials: Global Approach in Joining



Call For Papers

A new Special Issue *Welding and Soldering Materials: Global Approach in Joining* (<http://www.ijmsa.org/sinfo/123036>) has been launched in *International Journal of Materials Science and Applications* (<http://www.ijmsa.org>). This Special Issue intends to collect research achievements concerning Welding and Soldering. Novel insights as well as fundamental research on the topics are warmly welcomed. Your submissions along with your ingenious works are expected.

Lead Guest Editor

Lead Guest Editor: Jayesh S

Affiliation: Department of Mechanical Engineering, School of Engineering, Cochin University of Science and Technology, Kochi, Kerala, India

Paper Submission

Potential authors are humbly requested to submit an electronic copy of their complete manuscript via <http://www.ajlifesciences.org/submission>

Topics of Interest Include (but not limited to):

- ◆ To find new light weight welding material
- ◆ To publish detailed reviews about welding materials
- ◆ To find new procedures which enhances the efficiency
- ◆ To find new lead free solder alloys
- ◆ To publish reviews in lead free solder alloys
- ◆ To find new efficient electronic materials for joining

Important Dates

Submission Deadline: **Apr. 30, 2020**

Publication Deadline: **Jun. 30, 2020**



Join as Guest Editor

For scholars who have intention to join the special issue as guest editor, please check out the link below:

<http://www.ijmsa.org/jsgt/123036>